10/084761

Sc. # 1087

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PATENT NUMBER and ISSUE DATE

U.S. **UTILITY** Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	, ,	EXAMINER	J
10084761	02/20/2002	438	460	2812	Cestiada	
*APPLICANT	S: Sawada	a Hiroshi;				
*CONTINUIN	G DATA VERIFIE	ับ:				
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* FOREIGN A	APPLICATIONS V	ERIFIED	:	•		
JAPAN 2001-	45134 02/21/2001					
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Foreign priority cla			es ⊋ no		ATTORNEY DOCKE	TNC
35 USC 119 conditions met ☐ yes ☐ no Verified and Acknowledged Examiners's initials					JCLA8894	
TITLE: Substrate cutting method					U.S.DEPT. OF COMM./PAT.& TM-PTO-436L(Rev 12-94	
		·			U.S.DEPT, OF COMMAPATA	10-1332(1:01-12-0
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**								
NOTICE OF ALLOWANCE MAILED			CLAIMS ALLOWED					
		Assistant Examiner	Total Claims		Print Claim for O.G			
ISSUE FEE				DRAWING				
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.	Print Fig.			
		Primary Examine						
TERMINAL		PREPARED FOR ISSUE	Application Examiner					
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